

is more than 0.1 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.1 N / 20mm when heated.

8. (Amended) A manufacturing method of a multilayer ceramic electronic component comprising steps of;

laminating a ceramic green sheet onto other ceramic green sheets, after manufacturing the ceramic green sheet by manufacturing method according to Claim 1,

and separating the carrier sheet from the ceramic green sheet by being heated or irradiated with UV.

9. (Amended) A carrier sheet for ceramic green sheets used for the manufacturing method of the ceramic green sheet according to Claim 1, comprising an adhesive layer separable by being heated or an adhesive layer separable by being cured with UV on one side of a base film.

Please add the following claims:

11. (New) A carrier sheet for ceramic green sheets used for the manufacturing method of the multilayer ceramic electronic component according to Claim 8, comprising an adhesive layer separable by being heated or an adhesive layer separable by being cured with UV on one side of a base film.

12. (New) The manufacturing method of the ceramic green sheet according to Claim 1, wherein a dynamic modulus of elastic of an adhesive forming the adhesive layer separable by being heated is in a range of 5×10^4 to 8×10^5 Pa at a temperature of 23 degrees C to 150 degrees C.

13. (New) The manufacturing method of the ceramic green sheet according to Claim 1, wherein an adhesive strength to stainless steel of the adhesive layer separable by being heated is more than 0.2 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.05 N / 20mm when heated.

14. (New) The manufacturing method of the ceramic green sheet according to Claim 1, wherein an adhesive strength at ordinary temperature (23 degrees C) to stainless steel of the adhesive layer separable by being cured with UV is more than 0.2 N / 20mm before UV irradiation and no more than 0.05 N / 20mm after UV irradiation.